

### SILICON STACKED GATE CMOS

### 65,536 WORD x 16 BIT CMOS MASK ROM

#### Description

The TC531024P/F is a 1,048,576 bit read only memory organized as 65,536 words by 16 bits.

The TC531024P/F is fabricated using Toshiba's advanced CMOS technology which results in high speed and low power features: access times of 120ns/150ns, an operating current of 40mA at 8.3MHz, and a standby current of 20 $\mu$ A.

The TC531024P/F is packaged in a standard 600mil 40-pin DIP or 525mil 40-pin SOP.

#### Features

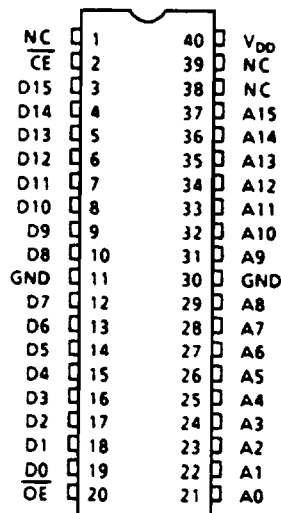
TC531024P/F	-12	-15
Power Supply	5V $\pm$ 5%	5V $\pm$ 10%
Access Time (max.)	120ns	150ns
Operating Current (max.)	40mA	35mA
Standby Current (max.)	20 $\mu$ A	20 $\mu$ A

- Single 5V power supply
- Fully static operation
- Inputs and outputs TTL compatible
- Three state outputs
- Package
  - TC531024P : DIP40-P-600
  - TC531024F : SOP40-P-525

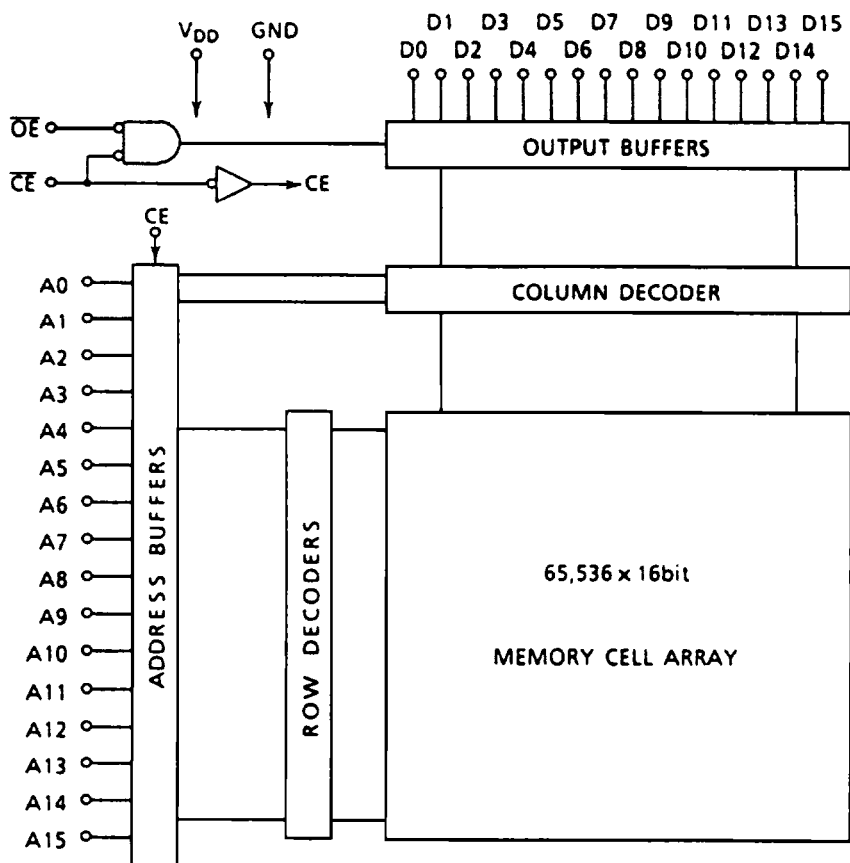
#### Pin Names

A0 ~ A15	Address Inputs
D0 ~ D15	Data Outputs
$\overline{OE}$	Output Enable Input
$\overline{CE}$	Chip Enable Input
V <sub>DD</sub>	Power Supply Voltage (+5V)
GND	Ground
NC	No Connection

#### Pin Connection (Top View)



## Block Diagram



## Operating Mode

MODE	CE	OE	A0 ~ 15	OUTPUTS	POWER
Read	L	L	Valid	Data Out	Operating
Standby	H	*	*	High-Z	Standby
Output Deselect	L	H	*	High-Z	Operating

H =  $V_{IH}$ , L =  $V_{IL}$ , \* =  $V_{IH}$  or  $V_{L}$

## Maximum Ratings

SYMBOL	ITEM	RATING	UNIT
$V_{DD}$	Power Supply Voltage	-0.5 ~ 7.0	V
$V_{IN}$	Input Voltage	-0.5 ~ $V_{DD}$	
$V_{OUT}$	Output Voltage	0 ~ $V_{DD}$	
$P_D$	Power Dissipation	1.0/0.6*	W
$T_{STRG}$	Storage Temperature	-55 ~ 150	°C
$T_{OPR}$	Operating Temperature	0 ~ 70	
$T_{SOLDER}$	Soldering Temperature • Time	260 • 10	

\* SOP

## DC Recommended Operating Conditions

SYMBOL	PARAMETER	-12			-15			UNIT
		MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
V <sub>DD</sub>	Power Supply Voltage	4.75	5.00	5.25	4.50	5.00	5.50	V
V <sub>IH</sub>	Input High Voltage	2.2	–	V <sub>DD</sub> + 0.3	2.2	–	V <sub>DD</sub> + 0.3	
V <sub>IL</sub>	Input Low Voltage	-0.3	–	0.8	-0.3	–	0.8	

## DC Characteristics (Ta = 0 ~ 70°C)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	MAX.	UNIT	
I <sub>LI</sub>	Input Leakage Current	V <sub>IN</sub> = 0 ~ V <sub>DD</sub>	–	±1.0	μA	
I <sub>LO</sub>	Output Leakage Current	$\overline{CE} = V_{IH}, V_{OUT} = 0 \sim V_{DD}$	–	±5.0		
I <sub>OH</sub>	Output High Current	V <sub>OH</sub> = 2.4V	-1.0	–	mA	
I <sub>OL</sub>	Output Low Current	V <sub>OL</sub> = 0.4V	3.2	–		
I <sub>DDS1</sub>	Standby Current	$\overline{CE} = 2.2V$	–	2	μA	
I <sub>DDS2</sub>		$\overline{CE} = V_{DD} - 0.2V$	–	20		
I <sub>DDO1</sub>	Operating Current	$\overline{CE} = V_{IL}, V_{IN} = V_{IH}/V_{IL}$ I <sub>OUT</sub> = 0mA	t <sub>cycle</sub> = 120ns	–	50	mA
			t <sub>cycle</sub> = 150ns	–	45	
I <sub>DDO2</sub>		$\overline{CE} = 0.2V,$ V <sub>IN</sub> = V <sub>DD</sub> - 0.2V/0.2V I <sub>OUT</sub> = 0mA	t <sub>cycle</sub> = 120ns	–	40	
			t <sub>cycle</sub> = 150ns	–	35	

## AC Characteristics (Ta = 0 ~ 70°C)

SYMBOL	PARAMETER	-12		-15		UNIT
		MIN.	MAX.	MIN.	MAX.	
t <sub>CYC</sub>	Cycle Time	120	–	150	–	ns
t <sub>ACC</sub>	Address Access Time	–	120	–	150	
t <sub>CE</sub>	Chip Enable Access Time	–	120	–	150	
t <sub>OE</sub>	Output Enable Access Time	–	70	–	70	
t <sub>CED</sub>	Output Disable Time from $\overline{CE}$	0	60	0	60	
t <sub>OED</sub>	Output Disable Time from $\overline{OE}$	0	60	0	60	
t <sub>OH</sub>	Output Hold Time	5	–	5	–	

## AC Test Conditions

Input Pulse Levels	2.4V/0.6V
Input Pulse Rise and Fall Times	5ns max.
Input Timing Measurement Reference Levels	2.2V/0.8V
Output Timing Measurement Reference Levels	2.0V/0.8V
Output Load	1 TTL Gate and C <sub>L</sub> = 100 pF

## Capacitance\* (Ta = 25°C, f = 1MHz)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	MAX.	UNIT
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 0V	–	10	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 0V	–	10	

\*This parameter is periodically sampled and is not 100% tested.

## Timing Waveforms

